

AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): KAMALESH K. SRIVASTAVA ET AL.				Docket No. FIS920030359US1	
Application No. 16/708,649	Filing Date 03/17/2004	Examiner P. CAO	Customer No. 29371	Group Art Unit 2814	Confirmation No. 2648
Invention: METHOD FOR FORMING ROBUST SOLDER INTERCONNECT STRUCTURES BY REDUCING EFFECTS OF SEED LAYER UNDERETCHING					
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<u>COMMISSIONER FOR PATENTS:</u>			<u>AUG 11 2005</u>		
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	12 -	20 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					

No additional fee is required for amendment.

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Signature

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Dated: August 11, 2005

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: KAMALESH K. SRIVASTAVA, ET AL.)
Serial No.: 10/708,649) Group Art Unit: 2814
Filed: March 17, 2004)
For: METHOD FOR FORMING ROBUST)
SOLDER INTERCONNECT)
STRUCTURES BY REDUCING EFFECTS) Confirmation No.: 2648
OF SEED LAYER UNDERETCHING)

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Office Action mailed July 12, 2005, please amend the Application as follows: